Supporting information

Low-temperature and self-reducible copper ink composed of copper-amino complexes and preset submicron copper seeds for high performance thick copper patterns on a flexible substrate

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Fig. S1 SEM micrographs of received copper particles (a) seeds A, (b) seeds B and (c) seeds C, and (d)-(f) are the corresponding particle size distribution.
Fig. S2 Microstructure of sintered patterns after heat treatment at 120 °C, 130 °C, 140 °C and 180 °C under nitrogen atmosphere.
Fig. S3 XRD patterns of seeds A, B and C.
Fig. S4 Relative thermal decomposition analysis using TGA-DAT.